

### D24N20ZA-VB Datasheet N-Channel 200 V (D-S) MOSFET

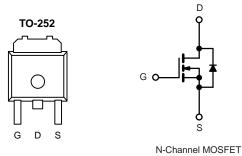
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)		
200	0.055 at V <sub>GS</sub> = 10 V	30		

### FEATURES

- Trench Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

• Primary Side Switch



<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_A = 25 \text{ °C}$ , unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V <sub>DS</sub>	200	V			
Gate-Source Voltage	V <sub>GS</sub>	± 20	v			
Continuous Drain Current $(T_1 = 175 \text{ °C})^b$	T <sub>C</sub> = 25 °C	I_	30			
Continuous Drain Current $(T_J = 175 \text{ C})^2$	T <sub>C</sub> = 125 °C	I <sub>D</sub>	25			
Pulsed Drain Current	I <sub>DM</sub>	160	А			
Continuous Source Current (Diode Conduction)	۱ <sub>S</sub>	28				
Avalanche Current	I <sub>AS</sub>	3				
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	18	mJ		
Maximum Davier Dissinction	T <sub>C</sub> = 25 °C	Pn	96 <sup>b</sup>	w		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	ГD –	3 <sup>a</sup>			
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
	t ≤ 10 s	- R <sub>thJA</sub>	15	18	°C/W	
Junction-to-Ambient <sup>a</sup>	Steady State		40	50		
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.85	1.1		

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.

Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	200			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μA	
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$			250	250	
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	40			А	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}$					
	R <sub>DS(on)</sub>	$V_{GS}$ = 10 V, I <sub>D</sub> = 3 A, T <sub>J</sub> = 125 °C	0.060				
Drain-Source On-State Resistance <sup>b</sup>		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}, \text{ T}_{J} = 175 \text{ °C}$		0.070		Ω	
		V <sub>GS</sub> = 6 V, I <sub>D</sub> = 3 A		0.092			
Forward Transconductanceb	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 3 A		35		S	
Dynamic <sup>a</sup>							
Input Capacitance	C <sub>iss</sub>			1800			
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 25 V, F = 1 MHz		180		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			80			
Total Gate Charge <sup>c</sup>	Qg			34	51		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 100 V, $V_{GS}$ = 10 V, $I_D$ = 3 A		8		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12		1	
Gate Resistance	R <sub>g</sub>		0.5		2.9	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 100 V, R <sub>L</sub> = 5.2 $\Omega$		50	75	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_{D} \cong$ 3 A, $V_{GEN}$ = 10 V, $R_{g}$ = 2.5 $\Omega$		30	45		
Fall Time <sup>c</sup>	t <sub>f</sub>			60	90	l .	
Source-Drain Diode Ratings and Char	acteristics (1	Γ <sub>C</sub> = 25 °C)		·			
Pulsed Current	I <sub>SM</sub>				5	А	
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	I <sub>F</sub> = 3 A, V <sub>GS</sub> = 0 V		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 3 A, dl/dt = 100 A/μs		180	250	ns	

Notes:

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

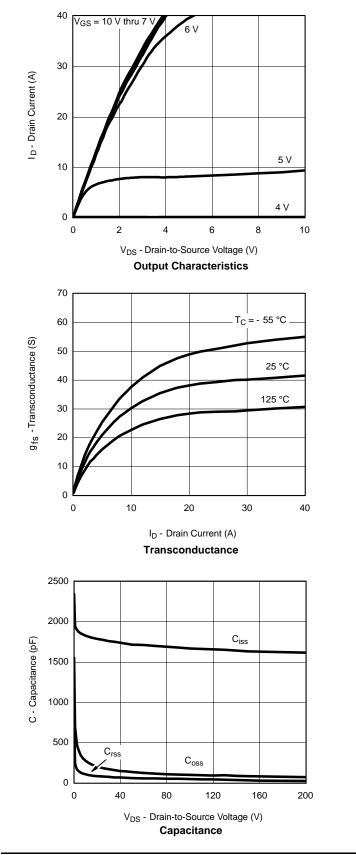
c. Independent of operating temperature.

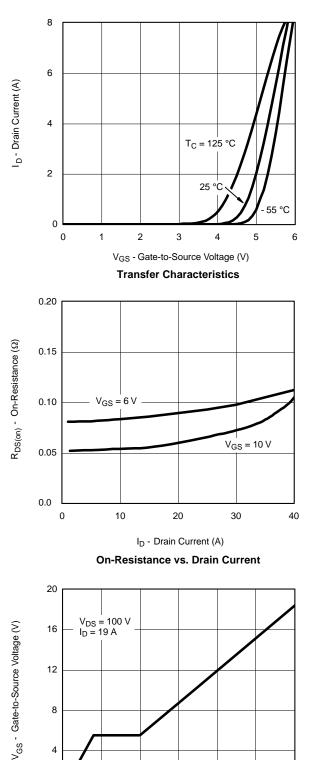
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Qg - Total Gate Charge (nC)

Gate Charge

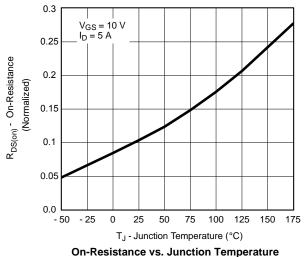


T<sub>J</sub> = 25 °C

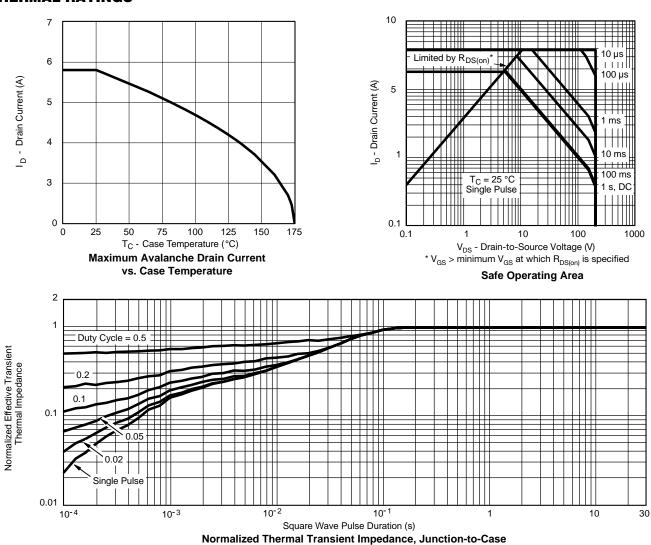
0.9

1.2

#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)







100

10

1

0

0.3

T<sub>J</sub> = 150 °C

0.6

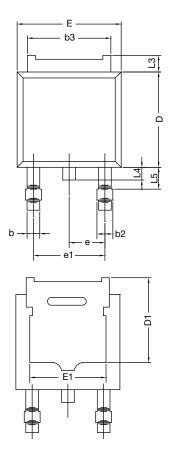
Source-Drain Diode Forward Voltage

V<sub>SD</sub> - Source-to-Drain Voltage (V)

I<sub>S</sub> - Source Current (A)



## **TO-252AA CASE OUTLINE**





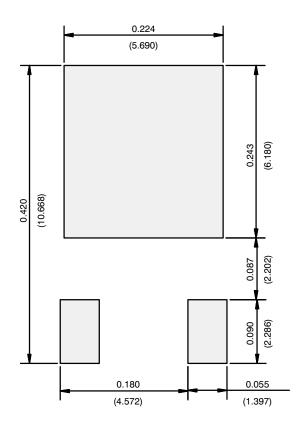
	MILLIN	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56	BSC	0.180	BSC	
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347					

#### Note

• Dimension L3 is for reference only.



### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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